

MSKSEMI 美森科

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT



PLED

SS24L-MS

Product specification

FEATURES

- deal for surface mount applications
- Easy pick and place
- Built-in strain relief
- Low forward voltage drop
- Ideal for surface mount applications
- Easy pick and place
- Built-in strain relief
- Low forward voltage drop

MACHANICAL DATA

- Case: Molded plastic
- Epoxy: UL 94V-0 rate flame retardant
- Metallurgically bonded construction
- Polarity: Color band denotes cathode end
- Mounting position: Any
- Weight: 0.063 grams


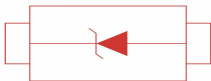

● **VOLTAGE RANGE**

40 Volts

● **CURRENT**

2.0 Ampere

Reference News

PACKAGE OUTLINE	PIN CONFIGURATION	Marking
		
SMA		

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating 25 °C ambient temperature unless otherwise specified.

Single phase half wave, 60Hz, resistive or inductive load.

For capacitive load, derate current by 20%.

TYPE NUMBER	SS24L-MS	UNITS
Maximum Recurrent Peak Reverse Voltage	40	V
Maximum RMS Voltage	28	V
Maximum DC Blocking Voltage	40	V
Maximum Average Forward Rectified Current See Fig. 1	2.0	A
Peak Forward Surge Current, 8.3 ms single half sine-wave superimposed on rated load (JEDEC method)	50	A
Maximum Instantaneous Forward Voltage at 2.0A	0.46	V
Maximum DC Reverse Current Ta=25 °C	0.2	mA
at Rated DC Blocking Voltage Ta=125 °C	50	mA
Typical Junction Capacitance (Note1)	170	pF
Typical Thermal Resistance RJA (Note 2)	88	C/W
Operating Temperature Range Tj	-55 to +125	°C
Storage Temperature Range Tstg	-55 to +150	°C

NOTES:

1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.
2. P.C.B. mounted with 0.2" x 0.2" (5.0 mm x 5.0 mm) copper pad areas

RATING AND CHARACTERISTIC CURVES (SS24L-MS)

FIG.1-FORWARD CURRENT DERATING CURVE

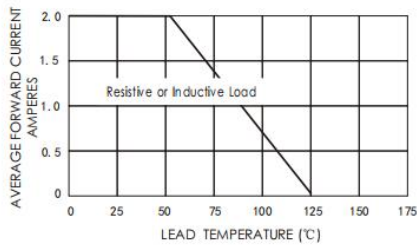


FIG.2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

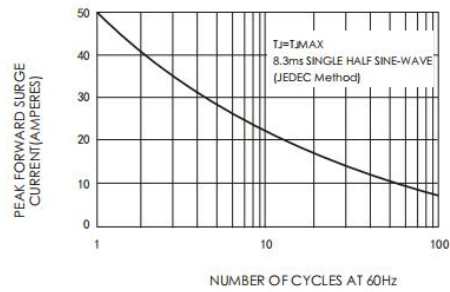


FIG.3-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

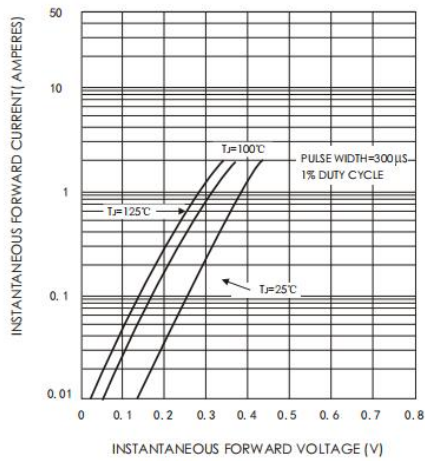


FIG.4-TYPICAL REVERSE CHARACTERISTICS

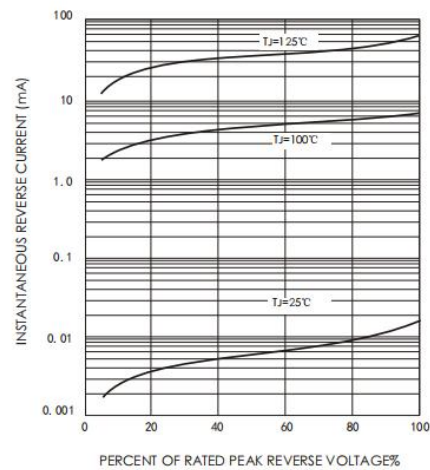
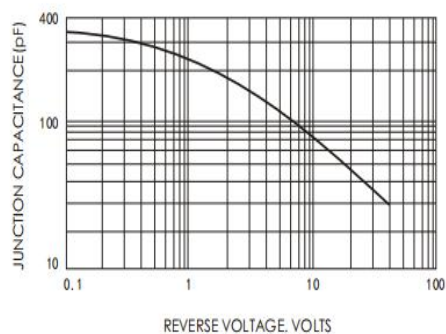
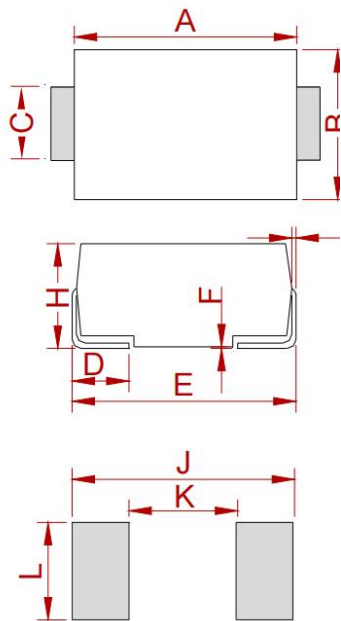


FIG.5-TYPICAL JUNCTION CAPACITANCE



PACKAGE MECHANICAL DATA



Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.25	4.65	0.167	0.183
B	2.50	2.90	0.098	0.114
C	1.35	1.65	0.053	0.065
D	0.76	1.52	0.030	0.060
E	4.93	5.28	0.194	0.208
F	0.051	0.203	0.002	0.008
G	0.15	0.31	0.006	0.012
H	1.98	2.41	0.078	0.095
J	6.50		0.256	
K		2.30		0.090
L	1.70		0.067	

REEL SPECIFICATION

P/N	PKG	QTY
SS24L-MS	SMA	2000

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